

3576 U.S. PTO
10/078016



10027

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10078016	FILING DATE 02/15/2002	CLASS 427	SUBCLASS 685	GAU 1762	EXAMINER THANH NGUYEN
----------------------	---------------------------	--------------	-----------------	-------------	--------------------------

**APPLICANTS: Herner Scott;

**CONTINUING DATA VERIFIED: None
TN

** FOREIGN APPLICATIONS VERIFIED: None
TN

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☒ no
35 USC 119 conditions met ☐ yes ☒ no
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO
A5031/T43300

TITLE : High throughput process for the formation of a refractory metal nucleation layer

U.S. DEPT. OF COMM./PAT. & TM.-PTO-4352 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
Amount Due		Sheets Drwg.	Figs. Drwg.
Date Paid		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
PREPARED FOR ISSUE		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)

BEST AVAILABLE COPY